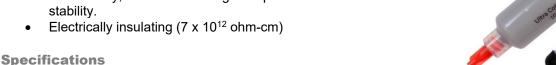


Datasheet revision 1.6 www.chipquik.com

Heat Sink Compound - Grey Ultra Conductive 20g Syringe 10cc

Product Highlights

- Lead-Free / RoHS 3 Compliant / REACH Compliant
- Ultra High-Density Thermal Paste. Grey, noncuring, flowable, thermally conductive heat sink compound. Heavily filled with heat-conductive metal oxide. Provides extremely high thermal conductivity, low bleed and high temperature stability.



Specifications

Viscosity: 95,000 cP (95,000 mPa·s)

Density: 2.5g/cc
Thermal Conductivity: 4.3 W/m·K
Thermal Resistance: 0.06 °C*cm²/W
Electrical Volume Resistivity: 7 x 10¹² ohm-cm
Dielectric Strength: 0.67 MV/m (17V/mil)
Operating Temperature (Continuous): -40 to 150°C (-40 to 302°F)

Operating Temperature (Continuous): -40 to 130 C (-200 C)

Operating Life: >8 years *dependent on several factors, test in application to ensure suitability

Size: 20g Syringe (10cc)

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an application temperature of 20-25°C (68-77°F) before use.

Shelf Life

>24 months

Stencil Life

>7 days @ 20-70% RH 22-28°C (72-82°F)

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.



Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m·K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G
8.5	0.03	2.5	Grey	Syringe	1	TC3-1G
8.5	0.03	2.5	Grey	Syringe	3.5	TC3-3.5G
8.5	0.03	2.5	Grey	Syringe	10	TC3-10G